



PATENT C7.

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Date

3/26/01

Nicole Bailey

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Robert A. Weaver, Gregory J. Wilson and Paul R. McHugh
Application No. : 09/733,608
Filed : December 8, 2000
For : METHOD AND APPARATUS FOR PROCESSING A
MICROELECTRONIC WORKPIECE AT AN ELEVATED
TEMPERATURE

Art Unit : 1742
Docket No. : 291958124US
Date : March 26, 2001

Box Non-Fee Amendment
Commissioner for Patents
Washington, DC 20231

PRELIMINARY AMENDMENT

Sir:

Please amend the application as follows:

In the Claims:

- A1 1 76. The method of claim 58 wherein thermally processing the selected
2 material includes thermally annealing a copper layer electrochemically-deposited on the
3 microelectronic workpiece.